Features

- 0603 0.5mm SMD LED
- High Brightness
- AlInGaP / InGaN Technology
- Small package
- High reliability
- Clear Lens

Applications

- Consumer Electronics
- Wearables
- Automobile After Market
- Industrial Equipment

Description

The IN-S63DBS5R5UW is a dual-color 0603, 4pin package with versatile design capabilities. It is a PCB type molding style LED which can be used in various applications.

Recommended Solder Pattern

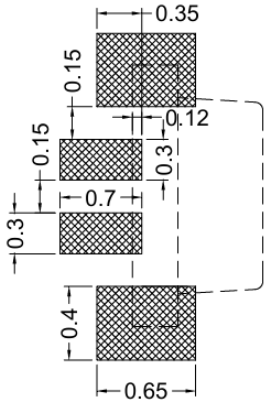
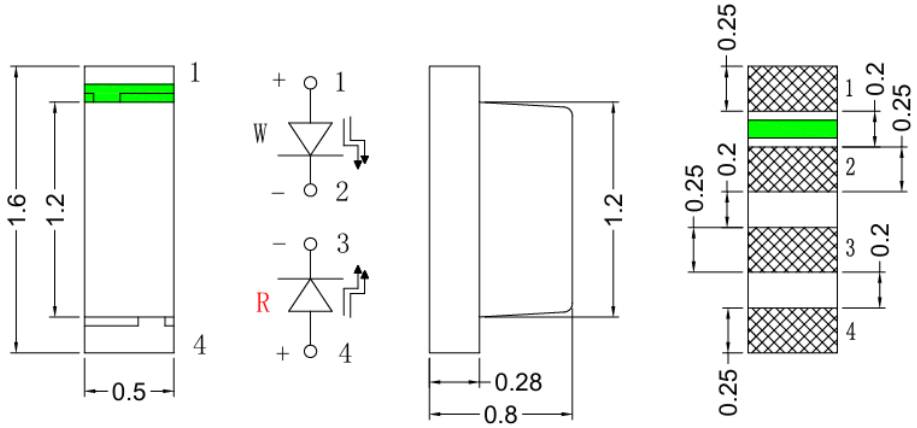


Figure 1. IN-S63DBS5R5UW Solder Pattern

Package Dimensions in mm



Notes.
1. All dimensions are in millimeters.
2. Tolerance is ± 0.10 mm unless otherwise noted

Figure 2. IN-S63DBS5R5UW Package Dimensions

Absolute Maximum Rating at 25°C (Note 1)

Product	Emission Color	P_d (mW)	I_F (mA)	I_{FP}* (mA)	V_R (V)	T_{OP} (°C)	T_{ST} (°C)
IN-S63DBS5R5UW	Red	65	25	70	5	-30°C~+85°C	-40°C~+90°C
	White	90		90			

Notes
1. Condition for IFP is pulse of 1/10 duty and 0.1msec width

ESD Precaution

ATTENTION: Electrostatic Discharge (ESD) protection

The symbol above denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlInGaP, GaN, or/and InGaN based chips are STATIC SENSITIVE devices. ESD precaution must be taken during design and assembly.
If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

Please be advised that normal static precautions should be taken in the handling and assembly of this device to prevent damage or degradation which may be induced by electrostatic discharge (ESD).

Electrical Characteristics T_A = 25℃ (Note 1)

Product	Emission Color	I_F(mA)	V_F(V)		λ (nm)			Viewing Angle	I^*_V(mcd)
			typ.	max	λ_D	λ_P	△λ	$2\theta_{1/2}$	typ.
IN-S63DBS5R5UW	Red	5	2.0	2.4	622	630	20	120	35
	White	5	2.9	3.1	X=0.25 Y=0.22	-	-	120	200

Notes
1. Performance guaranteed only under conditions listed in above tables.

Luminous Intensity (Iv) Bin:

Color	Bin Code	Spec. Range
Red	G2	23-28.5 mcd
	H1	28.5-35 mcd
	H2	35-45 mcd
	J1	45-56 mcd
White	L2	140-180 mcd
	M1	180-230 mcd
	M2	230-285 mcd
	N1	285-350 mcd

@5mA / Ta=25^{O} C, Tolerance: ± 10%

Dominant Wavelength (λD) Bin:

Color	Bin Code	Spec. Range
Red	A	615-620
	B	620-625
	C	625-630

@5mA / Ta=25^{O} C, Tolerance: ± 0.5nm

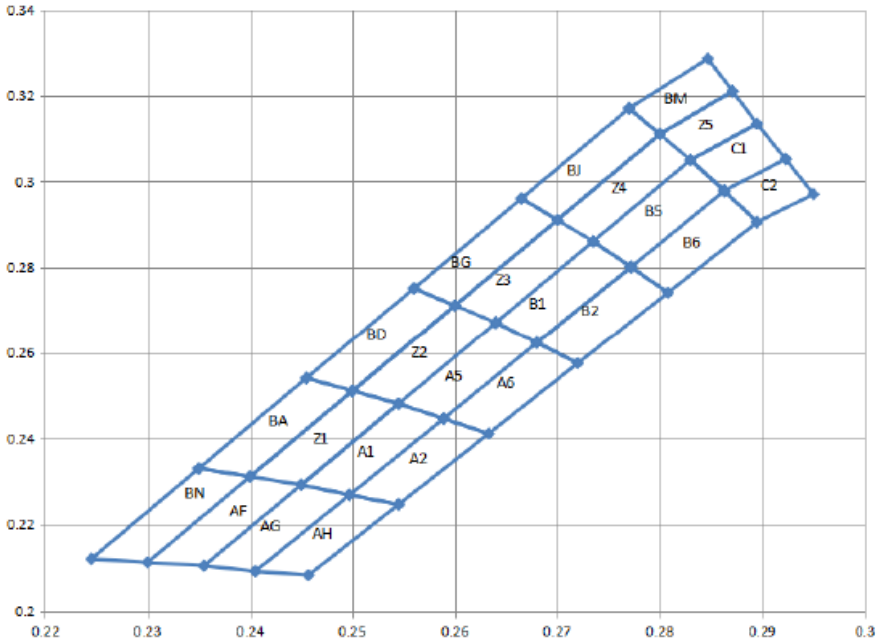
Forward Voltage (Vf) Bin:

Color	Bin Code	Spec. Range
Red	1	1.8-2.0
	2	2.0-2.2
	3	2.2-2.4
White	1	2.5-2.7
	2	2.7-2.9
	3	2.9-3.1

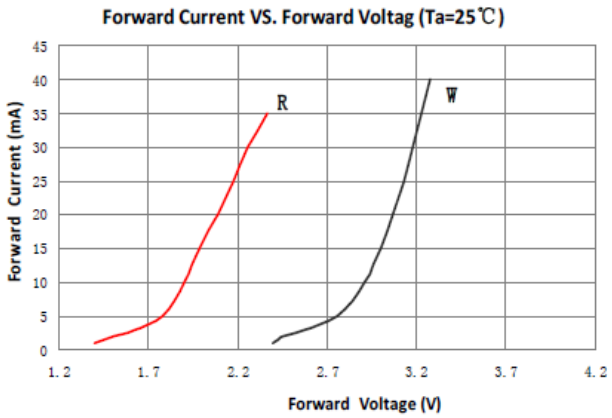
@5mA / Ta=25^{O} C, Tolerance: ± 0.05V

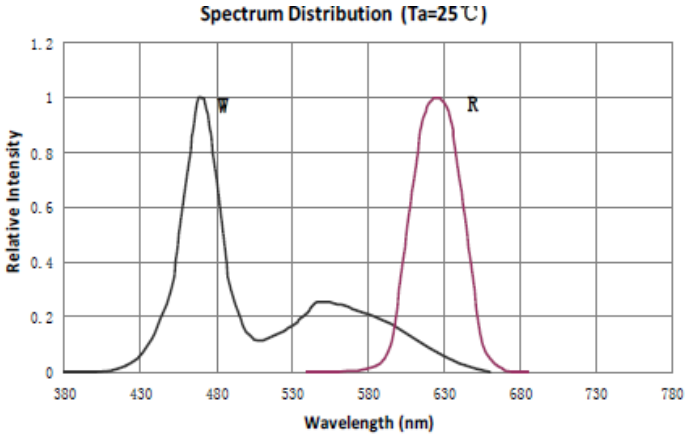
White Bin Range of Wavelength

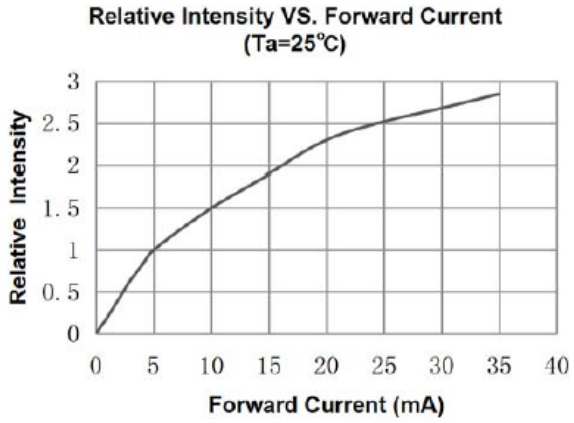
Bin Code	CIE-X	CIE-Y	Bin Code	CIE-X	CIE-Y	Bin Code	CIE-X	CIE-Y	Bin Code	CIE-X	CIE-Y
BN	0.2245	0.2118	AF	0.2300	0.2110	AG	0.2355	0.2102	AH	0.2405	0.2089
	0.2300	0.2110		0.2355	0.2102		0.2405	0.2089		0.2457	0.2080
	0.2400	0.2310		0.2450	0.2291		0.2497	0.2267		0.2545	0.2245
	0.2350	0.2329		0.2400	0.2310		0.2450	0.2291		0.2497	0.2267
BA	0.2350	0.2329	Z1	0.2400	0.2310	A1	0.2497	0.2267	A2	0.2497	0.2267
	0.2400	0.2310		0.2500	0.2510		0.2450	0.2290		0.2589	0.2445
	0.2500	0.2510		0.2545	0.2480		0.2545	0.2480		0.2633	0.2410
	0.2455	0.2540		0.2450	0.2291		0.2589	0.2445		0.2545	0.2245
BD	0.2455	0.2540	Z2	0.2500	0.2510	A5	0.2545	0.2480	A6	0.2589	0.2445
	0.2500	0.2510		0.2600	0.2710		0.2589	0.2445		0.2633	0.2410
	0.2600	0.2710		0.2640	0.2670		0.2680	0.2623		0.2720	0.2575
	0.2560	0.2750		0.2545	0.2480		0.2640	0.2670		0.2680	0.2623
BG	0.2560	0.2750	Z3	0.2600	0.2710	B1	0.2640	0.2670	B2	0.2720	0.2575
	0.2600	0.2710		0.2700	0.2910		0.2680	0.2623		0.2680	0.2623
	0.2700	0.2910		0.2735	0.2860		0.2772	0.2800		0.2772	0.2800
	0.2665	0.2960		0.2640	0.2670		0.2735	0.2860		0.2808	0.2740
BJ	0.2665	0.2960	Z4	0.27	0.291	B5	0.2735	0.2860	B6	0.2772	0.2800
	0.2700	0.2910		0.28	0.311		0.2772	0.2800		0.2808	0.2740
	0.2800	0.3110		0.283	0.305		0.2863	0.2978		0.2895	0.2905
	0.2770	0.3170		0.2735	0.286		0.2830	0.3050		0.2863	0.2978
BM	0.2770	0.3170	Z5	0.28	0.311	C1	0.2830	0.3050	C2	0.2863	0.2978
	0.2800	0.3110		0.2871	0.321		0.2863	0.2978		0.2895	0.2905
	0.2871	0.3210		0.2895	0.3134		0.2923	0.3052		0.2950	0.2970
	0.2847	0.3286		0.283	0.305		0.2895	0.3134		0.2923	0.3052

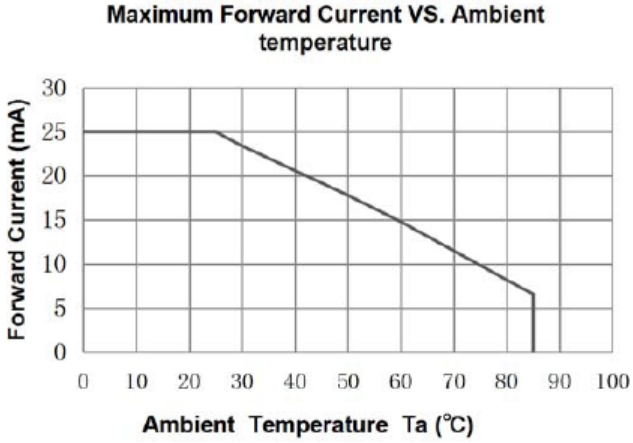


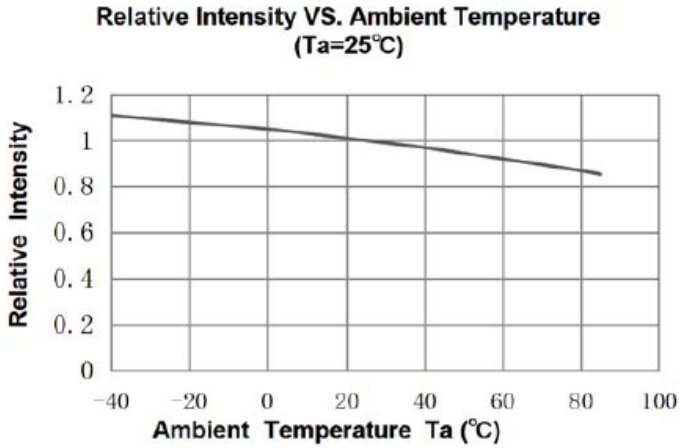
Typical Characteristic Curves



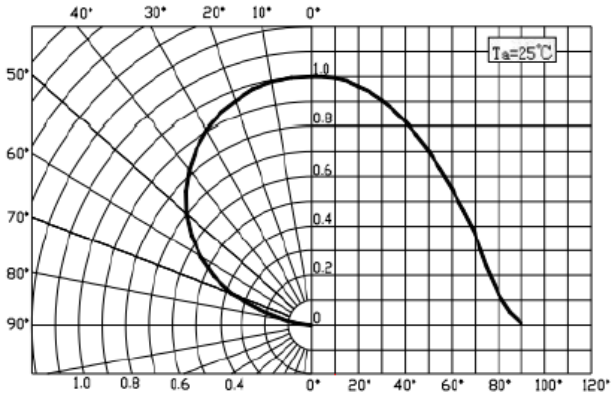








Typical Characteristic Curves – Radiation Pattern



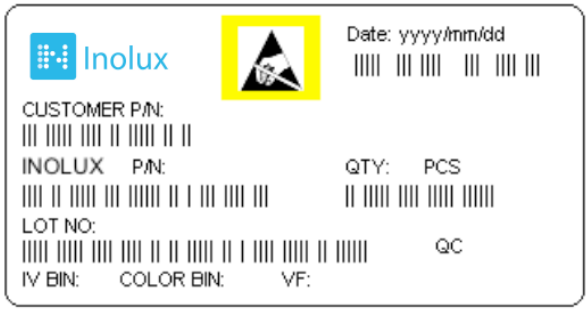
spatial distribution

Ordering Information

Product	Emission Color	Test Current I_F (mA)	Luminous Intensity I_V (mcd) (Typ.)	Forward Voltage V_F (V) (Typ.)	Orderable Part Number
IN-S63DBS5R5UW	Red	5	35	2.0	IN-S63DBS5R5UW
	White	5	200	2.9	

- Bin Range specified on page 3.

Label Specifications



Inolux P/N:

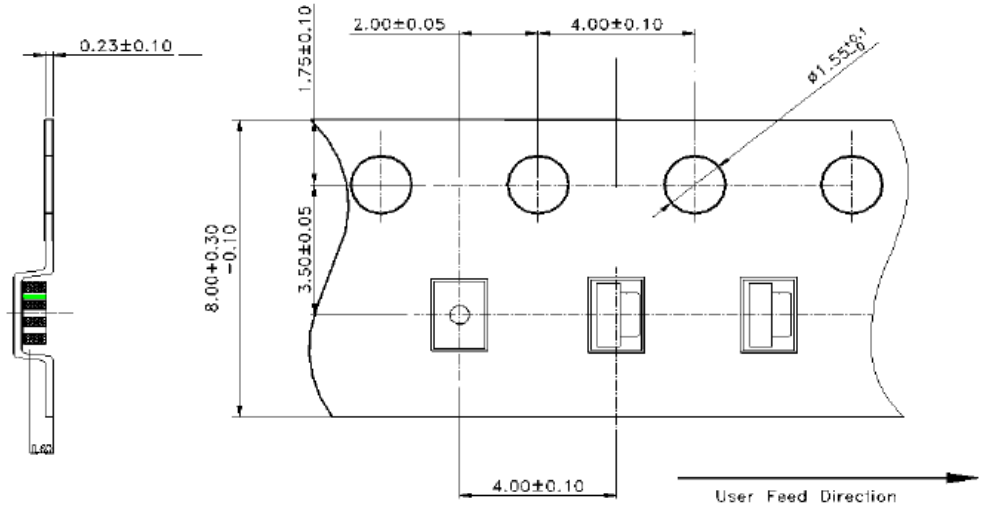
I	N	-	S	6	3	D	B	S	5	R	5	U	W	-				
			Material	Package		Variation		Orientation	Current	Color	Current	Lens	Color		Customized Stamp-off			
Inolux SMD			S = PCB Type	63DB = 1.6 x 0.8 x 0.5mm Dual chip				S = Side Mount	5= 5mA	R= 622nm	5= 5mA	U = Diffused	W= White					

Lot No.:

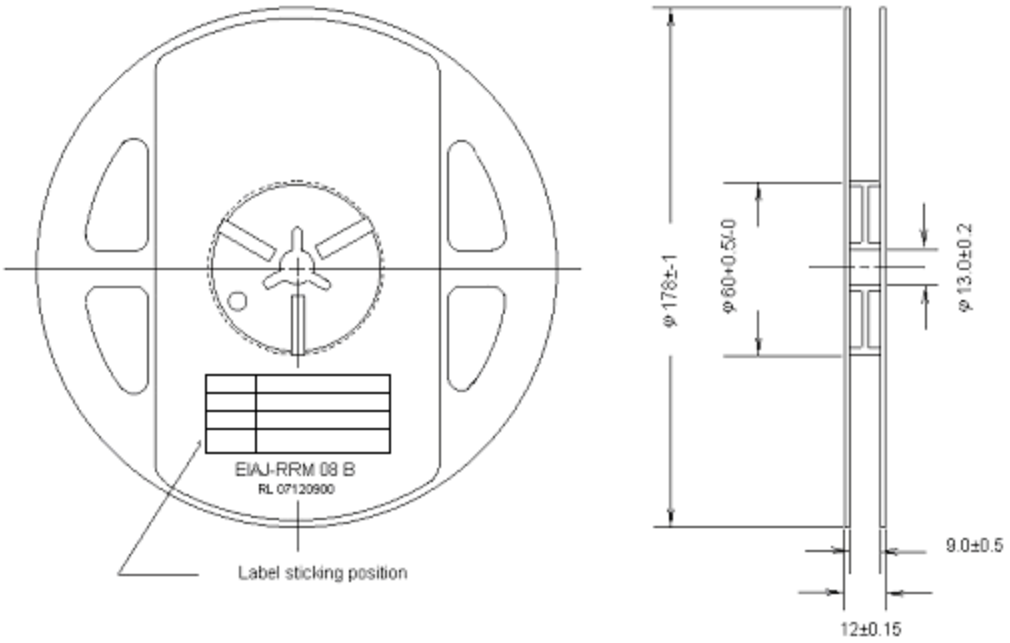
Z	2	0	1	7	01	24	001
Internal Tracker	Year (2017, 2018, …..)				Month	Date	Serial

Packaging Information: 4000pcs Per Reel

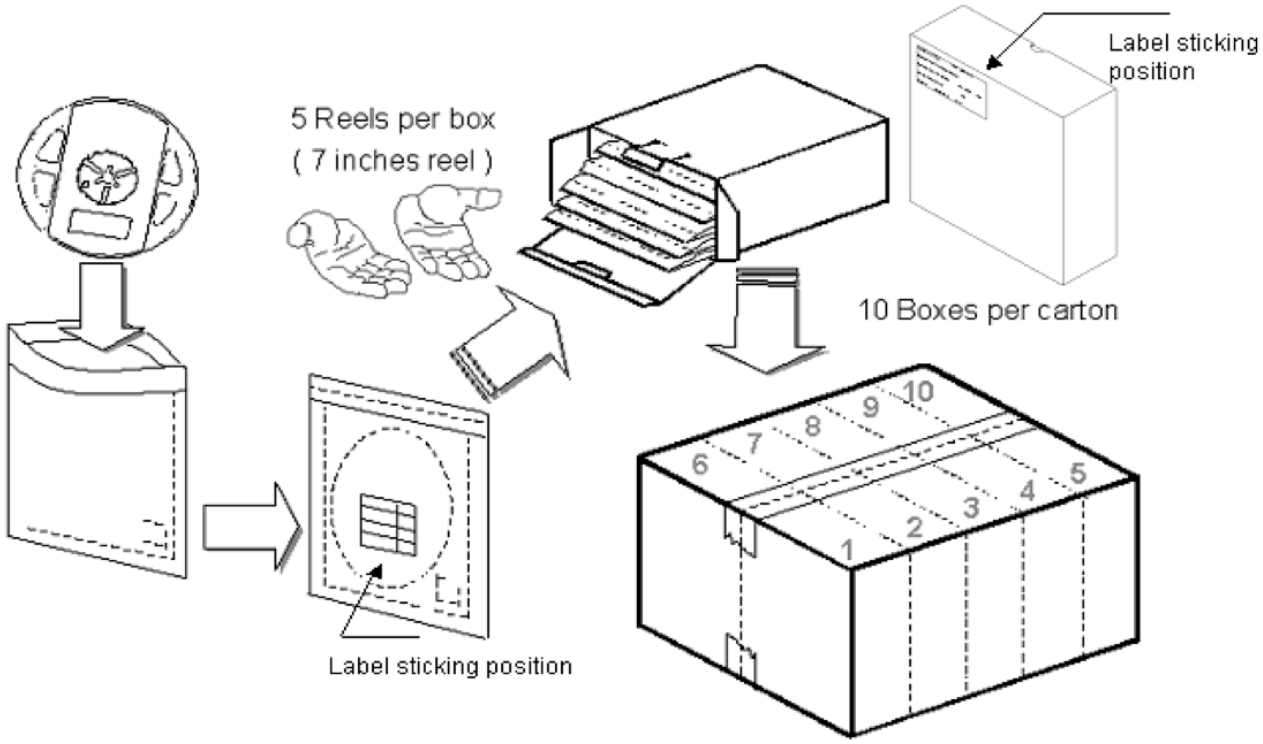
Tape Dimension



Reel Dimension



Packing Dimension



5 boxes per carton are available depending on shipment quantity.

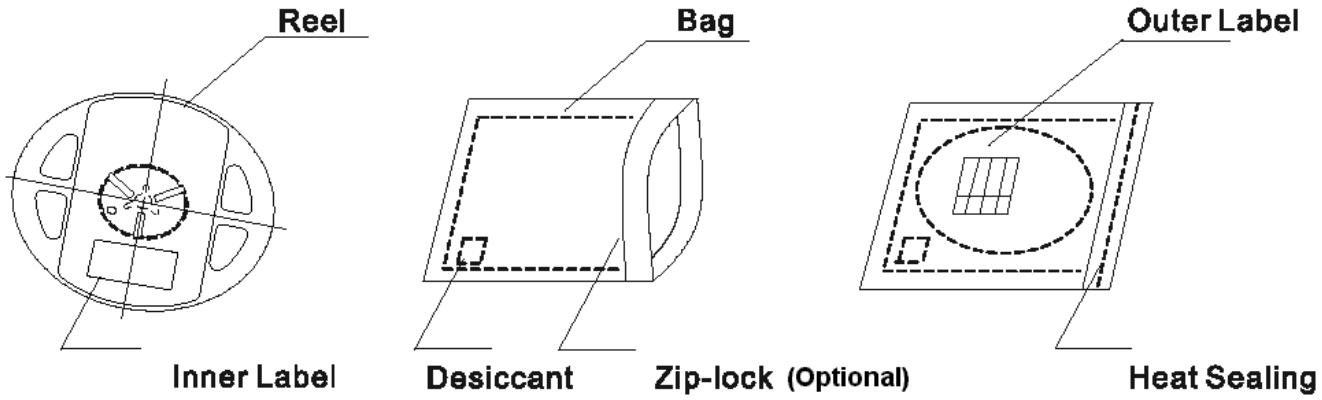
	Specification	Material	Quantity
Carrier tape	Per EIA 481-1A specs	Conductive black tape	4000pcs per reel
Reel	Per EIA 481-1A specs	Conductive black	
Label	IN standard	Paper	
Packing bag	220x240mm	Aluminum laminated bag/ no-zipper	One reel per bag
Carton	IN standard	Paper	Non-specified
Others: Each immediate box consists of 5 reels. The 5 reels may not necessarily have the same lot number or the same bin combinations of Iv, λ_D and Vf. Each reel has a label identifying its specification; the immediate box consists of a product label as well.			

Dry Pack

All SMD optical devices are **MOISTURE SENSITIVE**. Avoid exposure to moisture at all times during transportation or storage. Every reel is packaged in a moisture protected anti-static bag. Each bag is properly sealed prior to shipment.

Upon request, a humidity indicator will be included in the moisture protected anti-static bag prior to shipment.

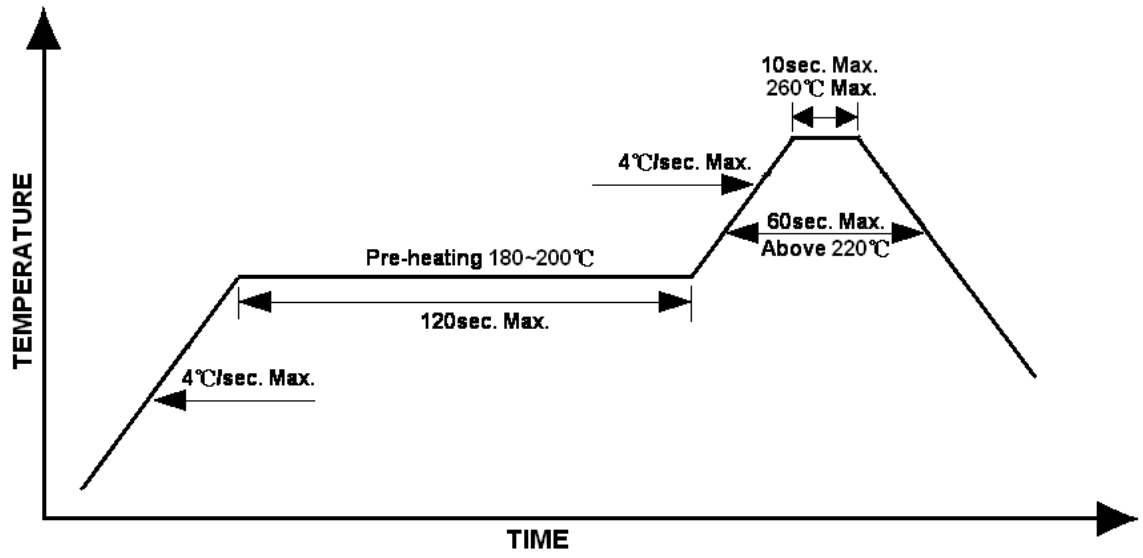
The packaging sequence is as follows:



Reflow Soldering

- Recommended tin glue specifications: melting temperature in the range of 178~192 ^{O}C
- The recommended reflow soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):

Lead-free Solder Profile



Precautions

- Avoid exposure to moisture at all times during transportation or storage.
- Anti-Static precaution must be taken when handling GaN, InGaN, and AlInGaP products.
- It is suggested to connect the unit with a current limiting resistor of the proper size. Avoid applying a reverse voltage.
- Avoid operation beyond the limits as specified by the absolute maximum ratings.
- Avoid direct contact with the surface through which the LED emits light.
- If possible, assemble the unit in a clean room or dust-free environment.

Reworking

- Rework should be completed within 5 seconds under 260 ^{O}C.
- The iron tip must not come in contact with the copper foil.
- Twin-head type is preferred.

Cleaning

Following are cleaning procedures after soldering:

- An alcohol-based solvent such as isopropyl alcohol (IPA) is recommended.
- Temperature x Time should be 50^{o}C x 30sec. or <30^{o}C x 3min
- Ultra sonic cleaning: < 15W/ bath; bath volume ≤ 1liter
- Curing: 100 ^{O}C max, <3min

Cautions of Pick and Place

- Avoid stress on the resin at elevated temperature.
- Avoid rubbing or scraping the resin by any object.
- Electro-static may cause damage to the component. Please ensure that the equipment is properly grounded. Use of an ionizer fan is recommended.

Revision History

Changes since last revision	Page	Version No.	Revision Date
Initial Release		V1.0	04-15-2020
Updated	P1	V1.1	09-04-2020
Updated	P3	V1.2	07-02-2021
Updated (PCN-PCB)	P1	V1.3	06-19-2025

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2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.